

In the claims-

Please amend the claims as follows:

1. (currently amended) A curable solid resin made by the process comprising the steps of:

A) providing a heat-settable mixture comprising a resin component comprising a thermosetting resin selected from the group consisting of epoxy resin, cyanate ester resin and bismaleimide resin, a curing agent component comprising a curing agent for said thermosetting resin and a particulate component, said heat-settable mixture having a curing temperature of between 120°C and 220°C, such that said heat-settable mixture forms a cured resin when heated to a temperature equal to or greater than said curing temperature and wherein said particulate component comprises particles of a rigid-rod polymer having diameters of from 0.1 to 1000 microns and that have a dissolution temperature wherein said rigid-rod polymer particles dissolve in said resin component at a dissolution temperature, which is between 20°C and 100°C below said curing temperature, said particulate component being present in an amount ranging from 5 to 35 weight percent of said heat-settable mixture such that said heat-settable resin mixture forms a heat-set mixture when said heat-settable resin mixture is heated to a temperature that is equal to or above said the dissolution temperature of said rigid-rod polymer and below said curing temperature of the heat-settable mixture;

B) heating the heat-settable resin mixture to a temperature that is equal to or above the said dissolution temperature of said rigid-rod polymer and below the said curing temperature of said heat-settable mixture for a sufficient time to form said heat-set mixture; and

C) cooling said heat-set mixture to a temperature below the said dissolution temperature of said rigid-rod polymer to form said curable solid resin.

2. (original) A curable solid resin composite body comprising fibers and a curable solid resin according to claim 1.

3. (currently amended) A curable solid resin according to claim 1 wherein said rigid-rod polymer ~~has~~ comprises a 1,4 phenylene backbone.

4. (currently amended) A curable solid resin according to claim 3 wherein benzoyl groups are attached to ~~said rigid polymer with a~~ 1,4 phenylene backbone ~~is PX1000 or PX1200.~~

5. (currently amended) A curable solid resin according to claim 1 wherein the said curing dissolution temperature is between about 30°C and 50°C below said curing temperature of said heat-settable mixture ~~is above 120°C.~~

6. (currently amended) A curable solid resin according to claim 1 wherein the said dissolution temperature of said rigid-rod polymer is between 75°C and 125°C.

7. (original) A cured resin formed by the step of heating the curable solid resin according to claim 1 to a temperature above said curing temperature for a sufficient time to cure said curable solid resin to form said cured resin.

8. (original) A cured composite body comprising fibers and a cured resin according to claim 7.

9. (currently amended) A cured resin according to claim 7 wherein said rigid-rod polymer ~~has~~ comprises a 1,4 phenylene backbone.

10. (currently amended) A cured resin according to claim 9 wherein benzoyl groups are attached to said rigid polymer with a 1,4 phenylene backbone is PX1000 or PX1200.

11. (currently amended) A cured resin according to claim 7 wherein the said curing dissolution temperature is between about 30°C and 50°C below said curing temperature of said heat-settable mixture is above 120°C.

12. (currently amended) A cured resin according to claim 7 wherein the said dissolution temperature of said rigid rod polymer is between 75°C and 125°C.

13. (currently amended) A method for making a curable solid resin comprising the steps of:

A) providing a heat-settable mixture comprising a resin component comprising a thermosetting resin selected from the group consisting of epoxy resin, cyanate ester resin and bismaleimide resin,, a curing agent component comprising a curing agent for said thermosetting resin and a particulate component, said heat-settable mixture having a curing temperature of between 120°C and 220°C, such that said heat-settable mixture forms a cured resin when heated to a temperature equal to or greater than said curing temperature and wherein said particulate component comprises particles of a rigid-rod polymer having diameters of from 0.1 to 1000 microns and that have a dissolution temperature wherein said rigid-rod polymer particles dissolve in said resin component at a dissolution temperature, which is between 20°C and 100°C below said curing temperature, said particulate component being present in an amount ranging from 5 to 35 weight percent of said heat-settable mixture such that said heat-settable resin mixture forms a heat-set mixture when said heat-settable resin mixture is heated to a temperature that is equal to or above said the dissolution temperature of said rigid rod polymer and below said curing temperature of the heat-settable mixture;

B) heating the heat-settable resin mixture to a temperature that is equal to or above the said dissolution temperature of said rigid rod polymer and below the said curing temperature of said heat-settable mixture for a sufficient time to form said heat-set mixture; and

C) cooling said heat-set mixture to a temperature below ~~the said~~ dissolution temperature ~~of said rigid rod polymer~~ to form said curable solid resin.

14. (currently amended) A method for making a curable solid prepreg comprising the steps of:

A) combining fibers with a heat-settable resin mixture to form a heat-settable prepreg layer, said heat-settable resin mixture comprising a resin component comprising a thermosetting resin selected from the group consisting of epoxy resin, cyanate ester resin and bismaleimide resin, a curing agent component comprising a curing agent for said thermosetting resin and a particulate component, said heat-settable mixture having a curing temperature of between 120°C and 220°C, such that said heat-settable mixture forms a cured resin when heated to a temperature equal to or greater than said curing temperature and wherein said particulate component comprises particles of a rigid-rod polymer having diameters of from 0.1 to 1000 microns and that have a dissolution temperature wherein said rigid-rod polymer particles dissolve in said resin component at a dissolution temperature, which is between 20°C and 100°C below said curing temperature, said particulate component being present in an amount ranging from 5 to 35 weight percent of said heat-settable mixture such that said heat-settable resin mixture forms a heat-set mixture when said heat-settable resin mixture is heated to a temperature that is equal to or above said the dissolution temperature ~~of said rigid rod polymer~~ and below said curing temperature ~~of the heat-settable mixture~~;

B) heating the heat-settable prepreg layer to a temperature that is equal to or above ~~the said~~ dissolution temperature ~~of said rigid rod polymer~~ and below ~~the said~~ curing temperature ~~of said heat-settable mixture~~ for a sufficient time to form said heat-set prepreg; and

C) cooling said heat-set prepreg to a temperature below ~~the said~~ dissolution temperature ~~of said rigid rod polymer~~ to form said curable solid prepreg.

15. (currently amended) A method for making a curable solid prepreg according to claim 14 wherein said rigid-rod polymer ~~has comprises~~ a 1,4 phenylene backbone.

16. (currently amended) A method for making a curable solid prepreg according to claim 14 wherein benzoyl groups are attached to said rigid polymer with a 1,4 phenylene backbone ~~is PX1000 or PX1200~~.

17. (currently amended) A method for making a curable solid prepreg according to claim 14 wherein the said curing dissolution temperature is between about 30°C and 50°C below said curing temperature of said heat-settable mixture is above 120°C.

18. (currently amended) A method for making a curable solid prepreg according to claim 14 wherein the said dissolution temperature ~~of said rigid-rod polymer~~ is between 75°C and 125°C.

19. (currently amended) A method for making a curable solid composite body comprising the steps of:

A) combining fibers with a heat-settable resin mixture to form at least two heat-settable prepreg layers, said heat-settable resin mixture comprising a resin component comprising a thermosetting resin selected from the group consisting of epoxy resin, cyanate ester resin and bismaleimide resin,, a curing agent component comprising a curing agent for said thermosetting resin and a particulate component, said heat-settable mixture having a curing temperature of between 120°C and 220°C, such that said heat-settable mixture forms a cured resin when heated to a temperature equal to or greater than said curing temperature and wherein said particulate component comprises particles of a rigid-rod polymer having diameters of from 0.1 to 1000 microns and that have a dissolution temperature wherein said rigid-rod polymer particles dissolve in said resin component at a dissolution temperature, which is between 20°C and 100°C below said curing temperature, said particulate component being present in an amount ranging from 5 to 35 weight percent of said heat-settable mixture such that said heat-settable resin mixture forms a heat-set mixture when said heat-settable

resin mixture is heated to a temperature that is equal to or above said the dissolution temperature of ~~said rigid rod polymer~~ and below said curing temperature of the heat-settable mixture;

B) placing said at least two heat-settable prepreg layers together to form a heat-settable prepreg body;

C) heating the heat-settable prepreg body at a temperature that is equal to or above said dissolution temperature of ~~said rigid rod polymer~~ and below said curing temperature of ~~said heat-settable mixture~~ for a sufficient time to form a heat-set prepreg body; and

D) cooling said heat-set prepreg body to a temperature below said dissolution temperature ~~the melting point of said rigid rod polymer~~ to form said curable solid composite body.

20. (currently amended) A method for making a curable solid composite body according to claim 19 wherein said rigid-rod polymer ~~has~~ comprises a 1,4 phenylene backbone.

21. (currently amended) A method for making a curable solid composite body according to claim 19 wherein benzoyl groups are attached to ~~said polymer with a~~ 1,4 phenylene backbone ~~is PX1000 or PX1200~~.

22. (currently amended) A method for making a curable solid composite body according to claim 19 wherein the said curing dissolution temperature is between about 30°C and 50°C ~~below said curing temperature of said heat-settable mixture is above 120°C~~.

23. (currently amended) A method for making a curable solid composite body according to claim 19 wherein the said dissolution temperature of said rigid rod polymer is between 75°C and 125°C.

24. (original) A method for making a cured composite layer comprising the step of heating the curable solid prepreg made according to claim 14 at a temperature equal to or above said curing temperature under ambient pressure for a sufficient time to form said cured composite layer.

25. (currently amended) A method for making a cured composite body comprising the step of heating the curable solid composite body made according to claim 19 ~~29~~ at a temperature equal to or above said curing temperature under ambient pressure for a sufficient time to form said cured composite layer.